

NTR0202PL, NVTR0202PL

MOSFET – Power, P-Channel, SOT-23

-20 V, -400 mA

Features

- Low $R_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life
 $R_{DS(on)} = 0.80 \Omega$, $V_{GS} = -10 \text{ V}$
 $R_{DS(on)} = 1.10 \Omega$, $V_{GS} = -4.5 \text{ V}$
- Miniature SOT-23 Surface Mount Package Saves Board Space
- NVT Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- DC-DC Converters
- Computers
- Printers
- PCMCIA Cards
- Cellular and Cordless Telephones

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	-20	V
Gate-to-Source Voltage – Continuous	V_{GS}	± 20	V
Continuous Drain Current @ $T_A = 25^\circ\text{C}$ Pulsed Drain Current ($t_p \leq 10 \mu\text{s}$)	I_D I_{DM}	-0.4 -1.0	A
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 1)	P_D	225	mW
Operating and Storage Temperature Range	T_J , T_{stg}	-55 to 150	$^\circ\text{C}$
Thermal Resistance – Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Source Current (Body Diode)	I_S	0.4	A
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 s	T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

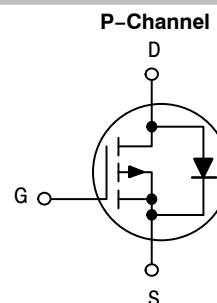
1. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.



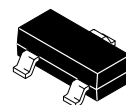
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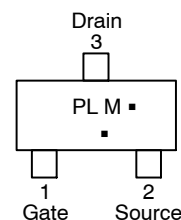
$V_{(BR)DSS}$	$R_{DS(on)}$ Typ	I_D MAX
-20 V	550 m Ω @ -10 V	-400 mA



MARKING DIAGRAM & PIN ASSIGNMENT



**SOT-23
CASE 318
STYLE 21**



PL = Specific Device Code
M = Date Code*
■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
NTR0202PLT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NTR0202PLT3G	SOT-23 (Pb-Free)	10000 / Tape & Reel
NVTR0202PLT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NTR0202PL, NVTR0202PL

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage (V _{GS} = 0 V, I _D = -10 μA) (Positive Temperature Coefficient)	V _{(BR)DSS}	-20	33		V mV/°C
Zero Gate Voltage Drain Current (V _{DS} = -20 V, V _{GS} = 0 V, T _J = 25°C) (V _{DS} = -20 V, V _{GS} = 0 V, T _J = 150°C)	I _{DSS}			-1.0 -10	μA
Gate-Body Leakage Current (V _{GS} = ± 20 V, V _{DS} = 0 V)	I _{GSS}			±100	nA

ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = -250 μA) (Negative Temperature Coefficient)	V _{GS(th)}	-1.1	-1.9 3.0	-2.3	V mV/°C
Static Drain-to-Source On-Resistance (V _{GS} = -10 V, I _D = -200 mA) (V _{GS} = -4.5 V, I _D = -50 mA)	R _{DS(on)}		0.55 0.80	0.80 1.10	Ω
Forward Transconductance (V _{DS} = -10 V, I _D = -200 mA)	g _{fs}		0.5		Mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	(V _{DS} = -5.0 V, V _{GS} = 0 V, F = 1.0 MHz)	C _{iss}	70		pF
Output Capacitance		C _{oss}	74		
Reverse Transfer Capacitance		C _{rss}	26		

SWITCHING CHARACTERISTICS (Note 3)

Turn-On Delay Time	(V _{DD} = -15 V, I _D = -200 mA, V _{GS} = -10 V, R _G = 6.0 Ω)	t _{d(on)}	3.0		ns
Rise Time		t _r	6.0		
Turn-Off Delay Time		t _{d(off)}	18		
Fall Time		t _f	4		
Total Gate Charge	(V _{DS} = -15 V, I _D = -200 mA, V _{GS} = -10 V)	Q _{TOT}	2.18		nC
Gate-Source Charge		Q _{GS}	0.41		
Gate-Drain Charge		Q _{GD}	0.40		

BODY-DRAIN DIODE CHARACTERISTICS (Note 2)

Diode Forward Voltage (Note 2) (I _S = -400 mA, V _{GS} = 0 V) (I _S = -400 mA, V _{GS} = 0 V, T _J = 150°C)	V _{SD}		-0.8 -0.65	-1.0	V
Reverse Recovery Time (I _S = -1.0 A, V _{GS} = 0 V, dI _S /dt = 100 A/μs)	t _{rr}		11.8		ns
	t _a		9		
	t _b		3		
Reverse Recovery Stored Charge (I _S = -1.0 A, V _{GS} = 0 V, dI _S /dt = 100 A/μs)	Q _{RR}		0.007		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

3. Switching characteristics are independent of operating junction temperature.

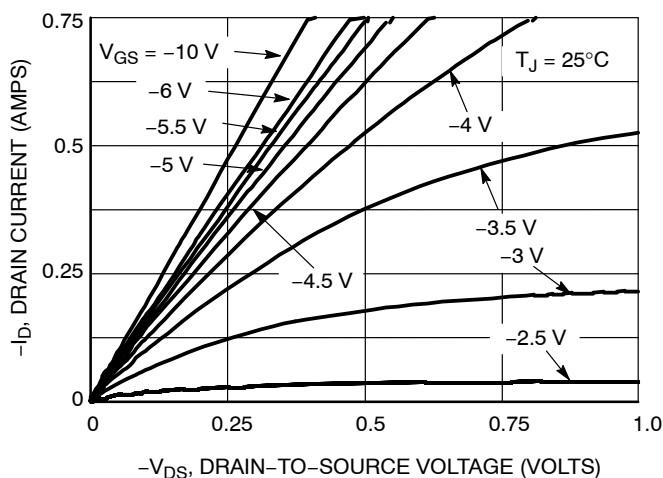


Figure 1. On-Region Characteristics

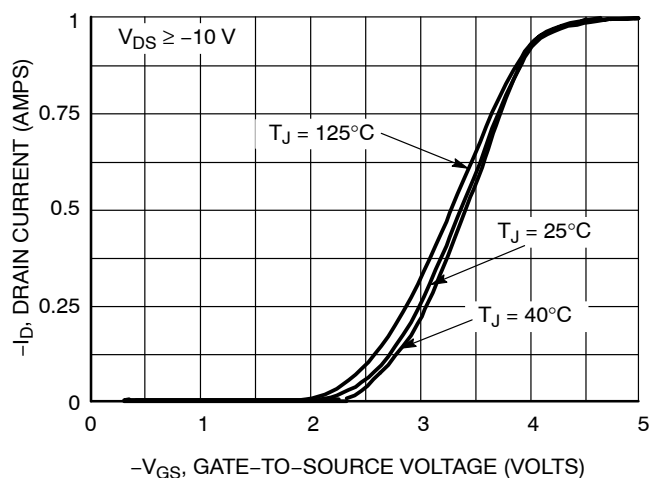


Figure 2. Transfer Characteristics

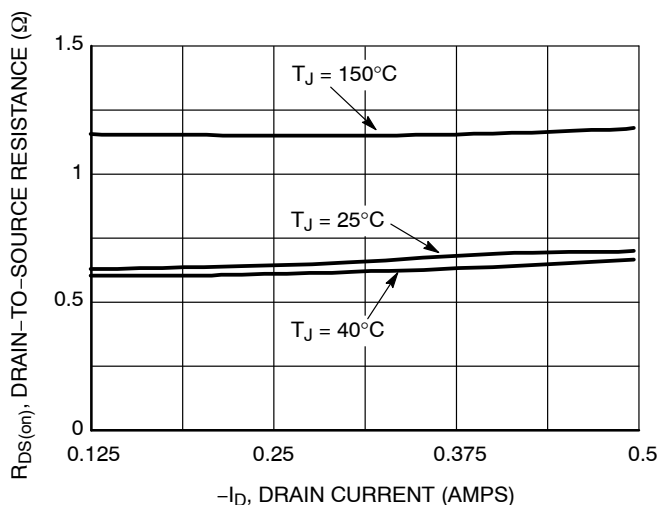


Figure 3. On-Resistance versus Drain Current

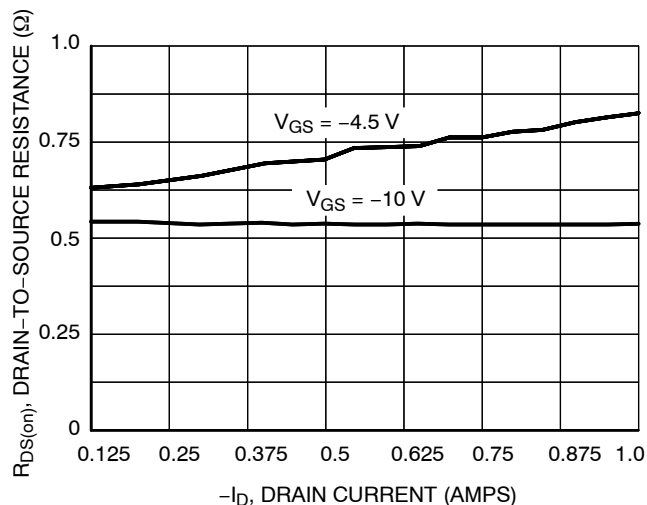


Figure 4. On-Resistance versus Drain Current and Gate Voltage

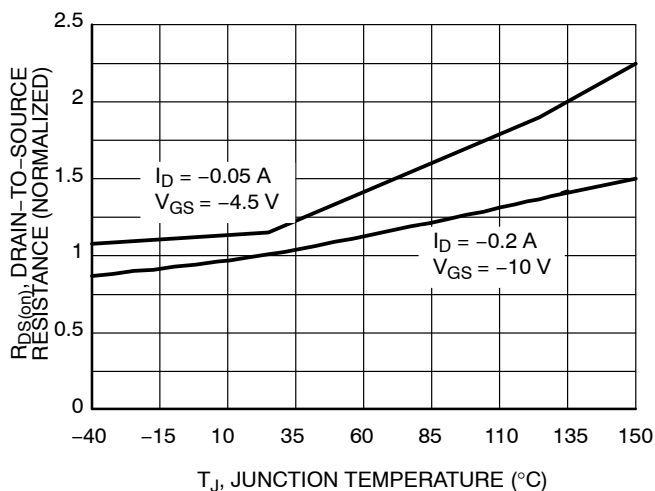


Figure 5. On-Resistance Variation with Temperature

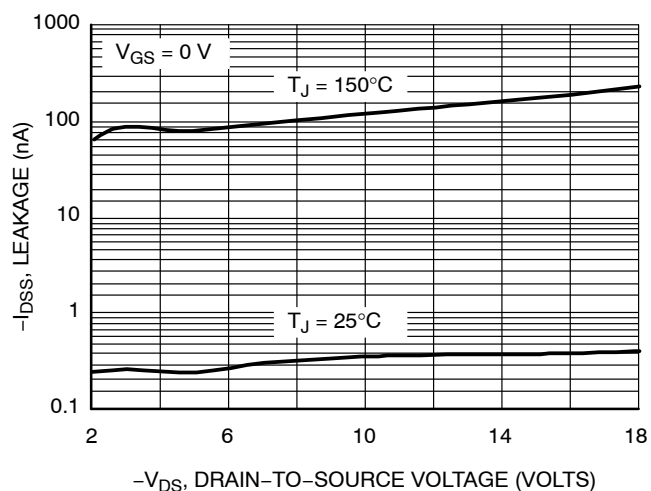


Figure 6. Drain-to-Source Leakage Current versus Voltage

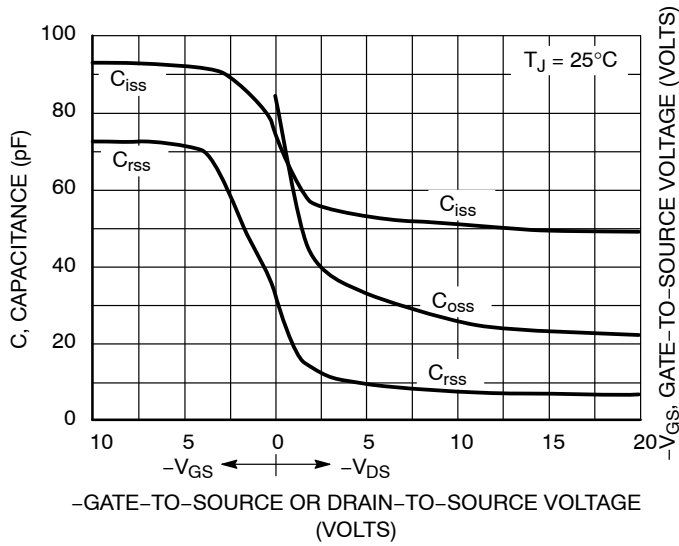


Figure 7. Capacitance Variation

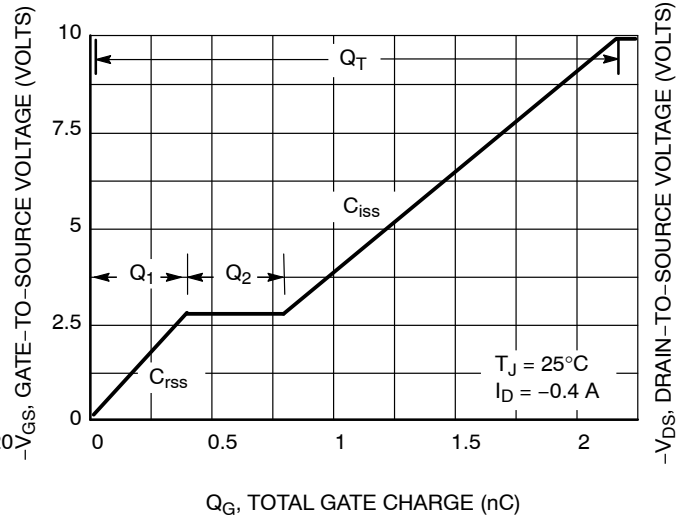


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

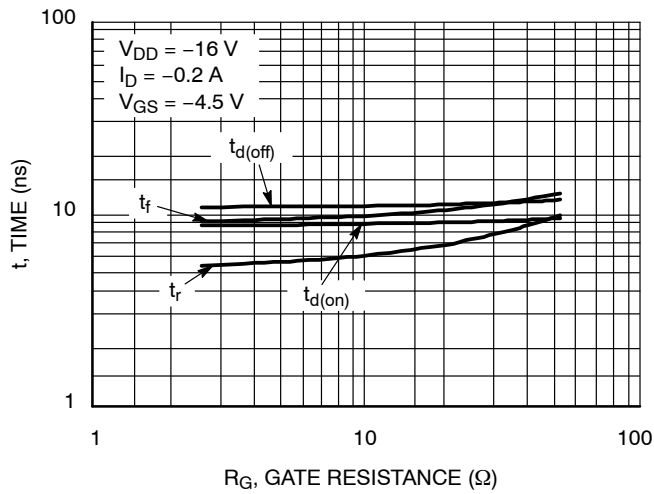


Figure 9. Resistive Switching Time Variation versus Gate Resistance

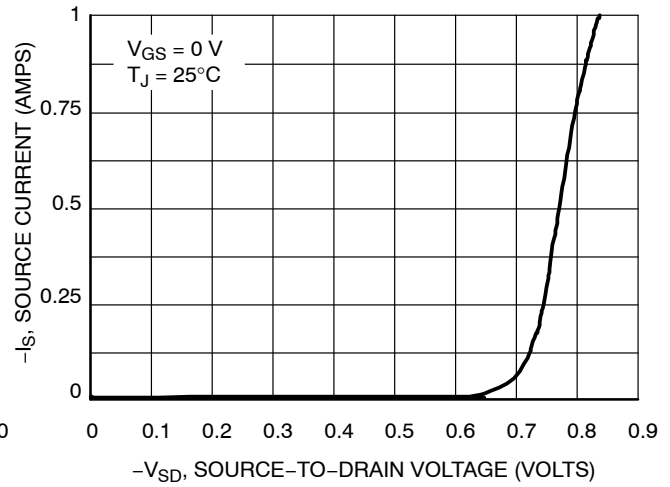


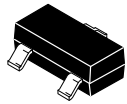
Figure 10. Diode Forward Voltage versus Current

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

ON



SOT-23 (TO-236) CASE 318-08 ISSUE AS

DATE 30 JAN 2018

SCALE 4:1

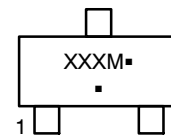


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE-ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

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